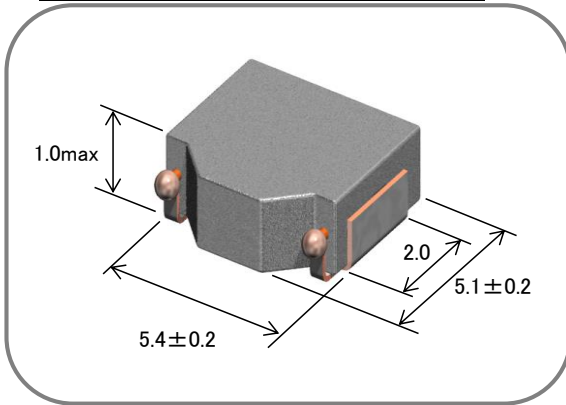


Component Image & Dimension



Features

Simulation Stage

- a) Small Footprint and Low Profile Design :
Footprint : 5.4 x 5.1 mm Typ.
Height : 1.0mm Max.
- b) High Power Handling Capability :
Small Copper Loss
Using Large Saturation Induction of Fe- based metals
- c) Flat inductance performance over temperature
based on the high curie temperature of the iron powder core material.
- d) Automatic Mounting in Tape&Reel Package.

Applications

Note Book & Mobile Computer, VRM,
Cellular Phone, HDD etc.

Electrical Specification

TDK Identification		Inductance		Test Freq. (kHz)	DC Resistance		Rated DC Current			
		at 0A (uH)	Tol. (%)		Spec. (m-Ohm)	Typ. (m-Ohm)	Idc 1		Idc 2	
							(A) max.	(A) typ.	(A) max.	(A) typ.
※	SPM5010T- R47M-LR	0.47	+/-20%	100	31.5 max	28.6	6.9	9.5	4.5	4.7
※	SPM5010T- 1R0M-LR	1.0	+/-20%	100	57.2 max	52.0	5.8	5.8	3.3	3.5
※	SPM5010T- 1R5M-LR	1.5	+/-20%	100	84.1 max	76.5	5.5	5.5	2.7	2.9
※	SPM5010T- 2R2M-LR	2.2	+/-20%	100	107.5 max	97.7	4.3	4.3	2.4	2.6
※	SPM5010T- 3R3M-LR	3.3	+/-20%	100	204.4 max	185.8	2.9	3.7	1.8	1.9
※	SPM5010T- 4R7M-LR	4.70	+/-20%	100	265.7 max	241.6	2.4	3.2	1.5	1.62
※	SPM5010T- 6R8M-LR	6.80	+/-20%	100	370.4 max	336.7	2.0	2.6	1.3	1.37
※	SPM5010T- 100M-LR	10.0	+/-20%	100	648.9 max	589.9	1.7	1.9	1.0	1.04

Note. Idc 1 : Based on the inductance change.(-30% Reduction from Nominal L Value)

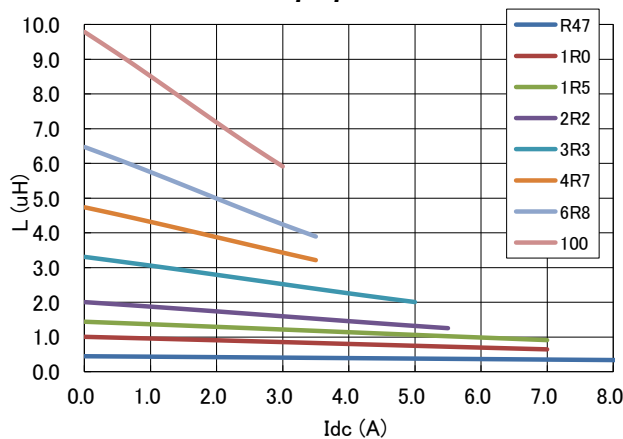
Idc 2 : Based on the self temperature rise. (+40 deg typ.)

Operating Temperature Range: -40 °C~+125 °C (including self temperature rise)

Caution: Please contact our sales person when you consider organic solvent or aqueous cleaning.

※ Simulation Data

Inductance vs.DC Superposition



Recommended pad layout

